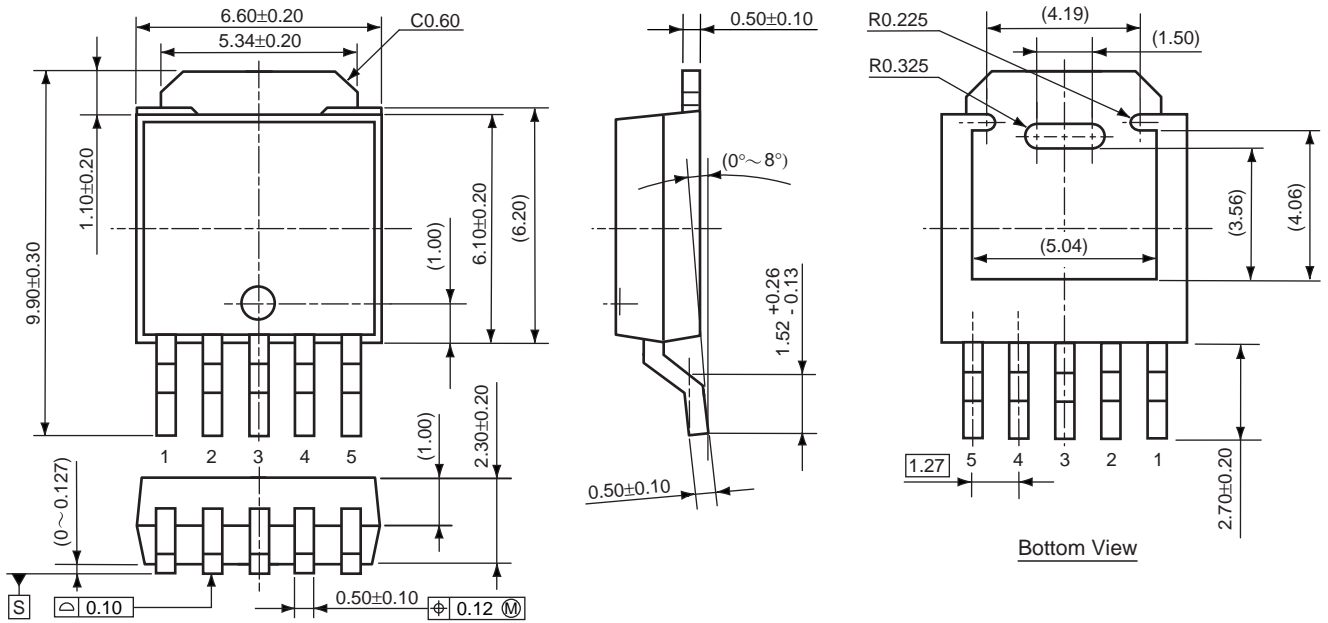


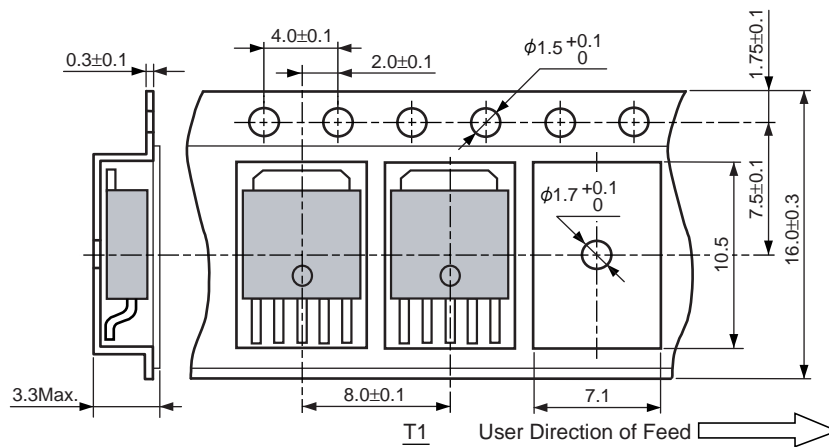
• TO-252-5-P2

Unit: mm

PACKAGE DIMENSIONS

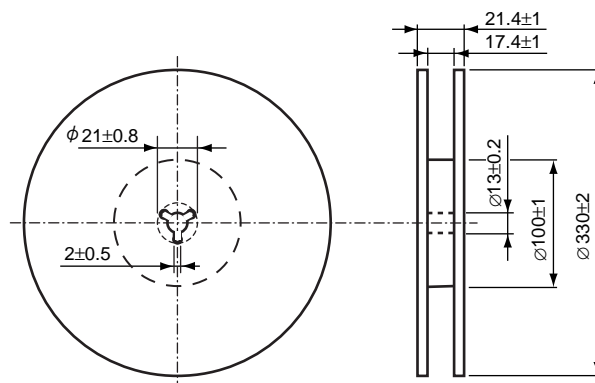


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-16Dc)

(1reel=3,000pcs)



### POWER DISSIPATION (TO-252-5-P2)

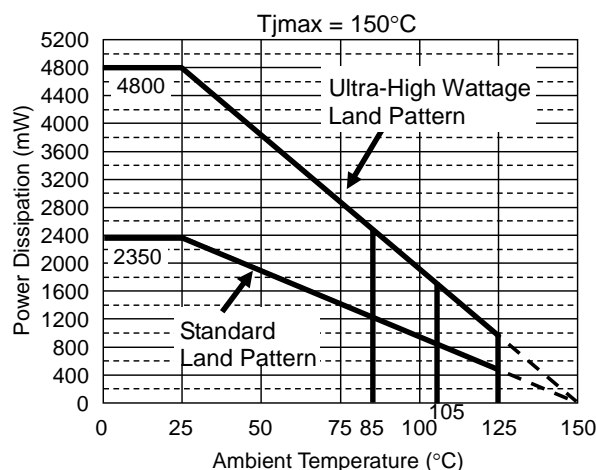
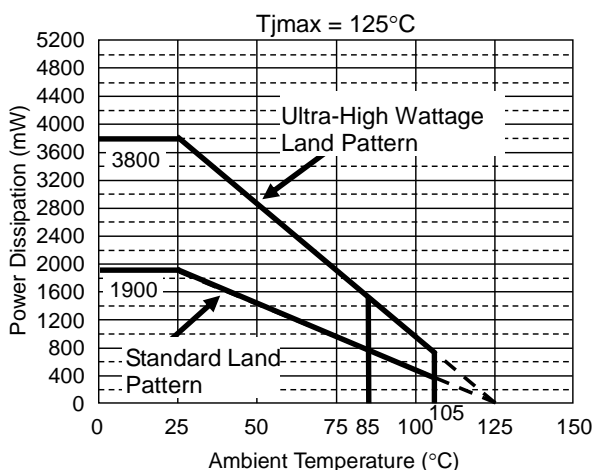
This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Land Pattern	Ultra-High Wattage Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)	Glass cloth epoxy plastic (Four-layers)
Board Dimensions	50 mm × 50 mm × 1.6 mm	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%	Top, Back side : Approx. 96% , 2nd, 3rd : Approx. 100%
Through-hole	φ0.5 mm × 24pcs	φ0.4 mm × 30 pcs

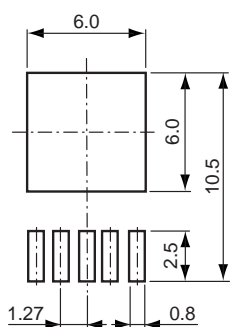
Measurement Result ( $T_a = 25^\circ\text{C}$ )

	Standard Land Pattern	Ultra-High Wattage Land Pattern
Power Dissipation	1900 mW ( $T_{jmax} = 125^\circ\text{C}$ ) 2350 mW ( $T_{jmax} = 150^\circ\text{C}$ )	3800 mW ( $T_{jmax} = 125^\circ\text{C}$ ) 4800 mW ( $T_{jmax} = 150^\circ\text{C}$ )
Thermal Resistance	$\theta_{ja} = 53^\circ\text{C/W}$ $\theta_{jc} = 17^\circ\text{C/W}$	$\theta_{ja} = 26^\circ\text{C/W}$ $\theta_{jc} = 7^\circ\text{C/W}$

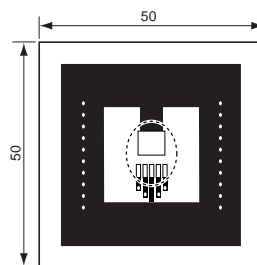


Power Dissipation vs. Ambient Temperature

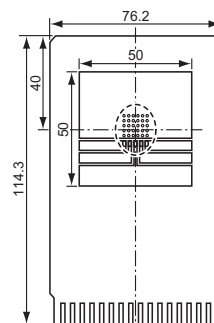
### Recommended Land Pattern



(Unit: mm)



Standard Land Patten



Ultra-High Wattage Land Pattern

○ IC Mount Area (Unit: mm)

Measurement Board Pattern